



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers: Workstation

Marketing Name / Model:
[List multiple models if applicable.]

HP Z2 SFF G1i Workstation ENERGY STAR

FCW-2404A

FCW-2404B

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP Inc. products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking or identification of location of parts or components requiring selective treatment, please contact [HP's Sustainability Contact](#).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment. An "X" in the list of components and parts indicates the product contains the component or part requiring selective treatment

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) with a surface greater than 10 sq cm	<input checked="" type="checkbox"/> Main board (MB) PCB <input checked="" type="checkbox"/> Solid state drive (SSD) PCB <input type="checkbox"/> Wireless WAN module (WWAN) PCB <input type="checkbox"/> Touch module PCB <input checked="" type="checkbox"/> Power supply PCB*3 <input checked="" type="checkbox"/> External Keyboard (KB) <input checked="" type="checkbox"/> External Mouse <input checked="" type="checkbox"/> Others: Memory PCB	8
Batteries, excluding Li-Ion batteries. This includes standard alkaline, coin or button style batteries	<input checked="" type="checkbox"/> RTC/CMOS battery <input type="checkbox"/> Others: _____	1
Li-Ion batteries. Includes all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, etc.)	Li-ion battery(ies) are attached to the product by: <input type="checkbox"/> screws <input type="checkbox"/> snaps <input type="checkbox"/> adhesive <input type="checkbox"/> other. Explain _____	0
Mercury-containing components. For example, mercury in lamps, display backlights, scanner lamps, switches, batteries		0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm. Includes background illuminated displays with gas discharge lamps	<input type="checkbox"/> Panel LCD	0
Cathode Ray Tubes (CRT)		0

EL-MF877-00
Template Revision D

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last updated May-2022

HP Inc. instructions for this template are available at [EL-MF877-01](#)

Item Description	Components and parts requiring selective treatments	Quantity of items included in product
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	<input checked="" type="checkbox"/> Power Supply capacitor(s) or condenser(s)	
External electrical cables and cords	<input checked="" type="checkbox"/> AC power cord <input type="checkbox"/> Audio, video or data cables <input type="checkbox"/> Other: <u>Output cable</u>	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants (not including external electrical cables and cords, PCBs or PCAs already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner. Include the cartridges, print heads, tubes, vent chambers, and service stations.		
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		
Components containing chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screwdriver	PH0
Screwdriver	PH1
Screwdriver	SL5
Screwdriver	T15

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure.

1. Remove to the cover from chassis.
2. Remove to the cover from chassis.
3. Remove to the Front Bezel from Chassis
4. Step4 Loose the holder and remove the GFX from the Chassis

5. Loosen the screws from CPU Cooler and remove it from the Motherboard. Remove the cooler fan duct from the Chassis.
6. Loosen the Screws from the CPU Cooler Fan and remove the Cooler fan
7. Loosen the Screws and remove PSU.
8. Step 8 Remove the PSU Power connector from the Motherboard.
9. Press the holder and remove the PSU from the chassis.
10. Remove the WLAN Antenna from the Motherboard.
11. Loosen the Screw and remove the Front IO Cover.
12. Loosen the screws from the Motherboard.
13. Remove the Motherboard from Chassis.
14. Remove the Memory from the Motherboard
15. Loosen the Screws from SSD and remove it.
16. Remove the CPU and WLAN from the Motherboard.
17. Step 17 Remove the Battery from the Motherboard.
18. Loosen the PSU Screws from top side
19. Loosen the PSU Screws from bottom side.
20. Remove the top cover by sliding horizontally away from bottom chassis.
21. Loosen the screws located on the solder mask side of PCA.
22. Loosen the screws located on the solder mask side of PCBA.
23. Flip over the PCBA with bottom chassis and lift loosening bottom chassis upward to 90 degrees angle for easy access to disconnect two connectors (fan power cable connector & inlet socket wire connector).
24. Remove the bottom chassis from the PCBA
25. Loosen the screws from the rear side and remove inlet socket away from the bottom chassis.
26. Loosen the 3 screws from the rear side and remove inlet socket away from the bottom chassis.
27. Use the screwdriver to cut off output mix cables to separate them from the PCBA.
28. Use the screwdriver to cut off electrolyte capacitor >2.5 cm for further treatment (Length: 4.8 cm)
29. Use the screwdriver to cut off electrolyte capacitor > 2.5cm for further treatment (Length: 2.5 cm).
30. Identify PCBA > 10 cm² for further treatment (CTL board 1: L: 5.7cm; W: 3.9 cm).
31. Identify PCBA > 10 cm² for further treatment (CTL board 2: L: 9 cm; W: 3.8cm)
32. Identify PCBA > 10 cm² for further treatment (CTL board 2: L: 13.5cm; W: 9cm)

Loosen the PSU Screws from bottom side. 3.2 Location of components requiring selective treatment. The photos and/or graphics below identify the location of the parts or components requiring selective treatment within the main unit. For End-of-Life product disassembly instructions of external accessories including external power supply (EPS), external keyboard (KB) external mouse and external cables and cords, refer to the following URL: [End-of-Life Product Disassembly Instructions \(hp.com\)](#)

Step1 Remove to the cover from chassis



Step2 Remove to the cover from chassis



Step3 Remove to the Front Bezel from chassis.



Step4 Loose the holder and remove the GFX from the Chassis.

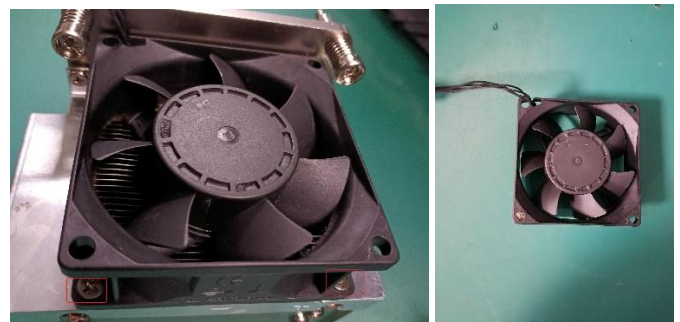


The GFX PCA PCB area surface is greater than 10sq cm.

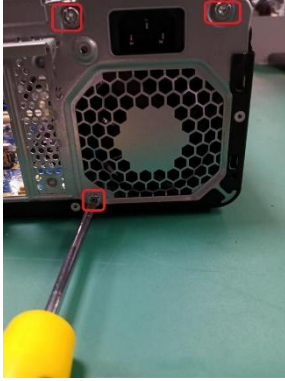
Step5 Loose the screws from CPU Cooler and remove it from the Motherboard. Remove the cooler fan duct from the Chassis.



Step6 Loose the Screws from the CPU Cooler Fan and remove the Cooler fan.



Step7 Lose the Screws and remove PSU.



Step8 Remove the PSU Power connector from the Motherboard.



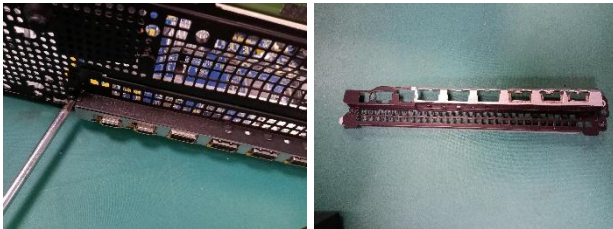
Step9 Press the holder and remove the PSU from the chassis.



Step10. Remove the WLAN Antenna from the Motherboard.



. Step11 Loose the Screw and remove the Front IO Cover.



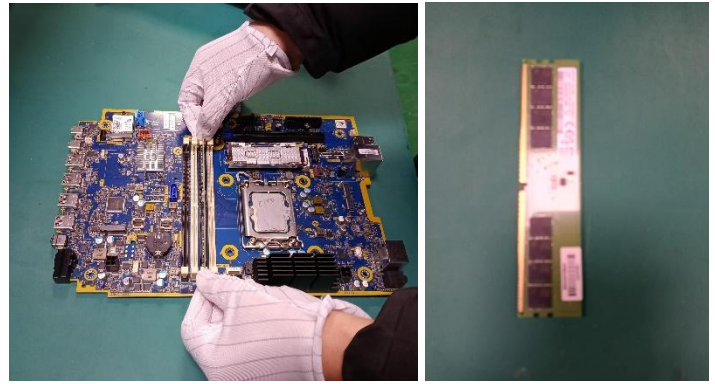
Step12 Loose the screws from the Motherboard.



Step13, Remove the Motherboard from Chassis.

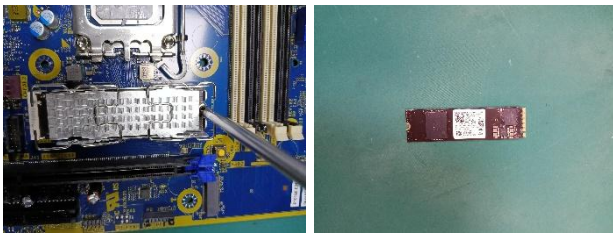


Step14, Remove the Memory from the Motherboard



Memory PCB area surface is greater than 10 sq cm

Step15 Loose the Screws from SSD and remove it.

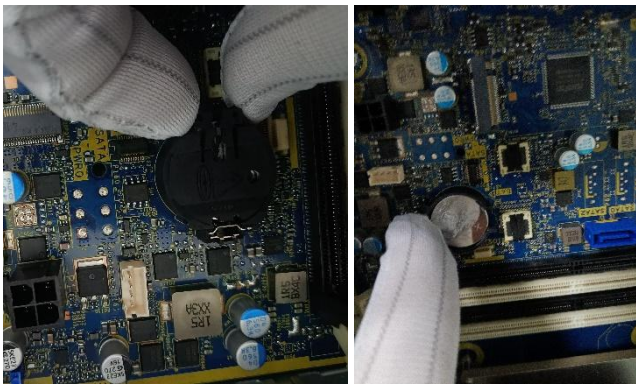


SSD PCA area surface is greater than 10 sq cm

Step16, Remove the CPU and WLAN from the Motherboard.



Step17 Remove the Battery from the Motherboard.



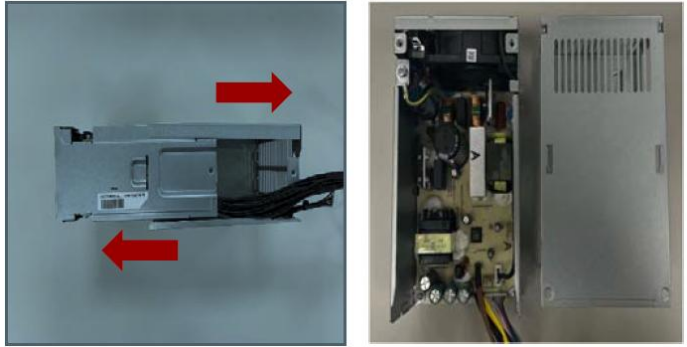
Step 18, Loose the PSU Screws from top side.



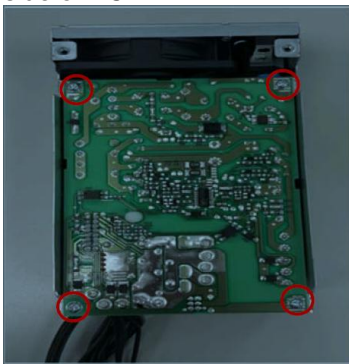
Step19, Loose the PSU Screws from bottom side.



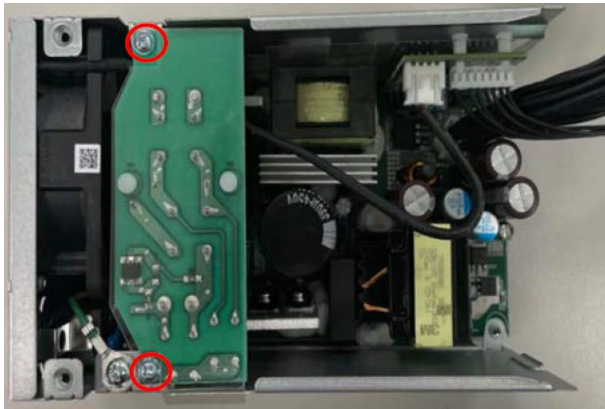
Step20, Remove the top cover by sliding horizontally away from bottom chassis.



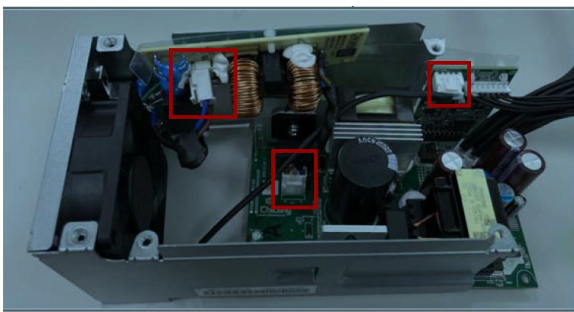
Step21, Loose the screws located on the solder mask side of PCA.



Step22, Loose the screws located on the solder mask side of PCBA.



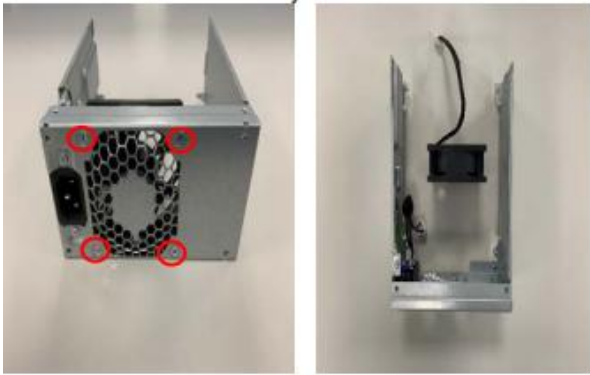
Step23 Flip over the PCBA with bottom chassis, and lift loosening bottom chassis upward to 90 degrees angle for easy access to disconnect two connectors (fan power cable connector & inlet socket wire connector).



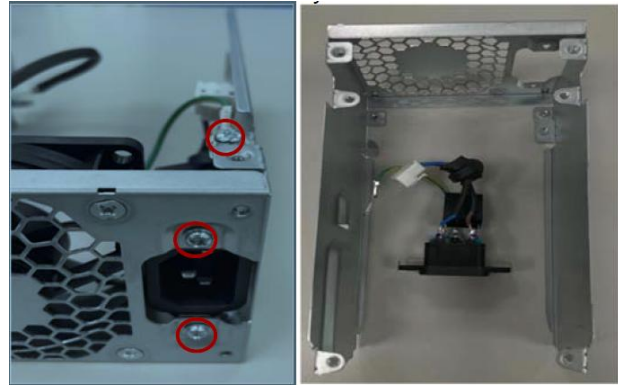
Step24 Remove the bottom chassis from the PCBA.



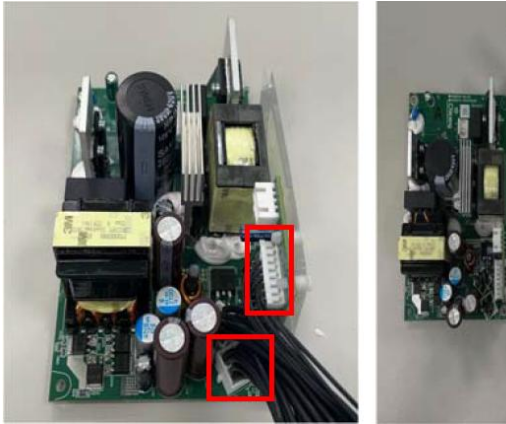
Step25. Loose the screws from the rear side and remove inlets socket away from the bottom chassis.



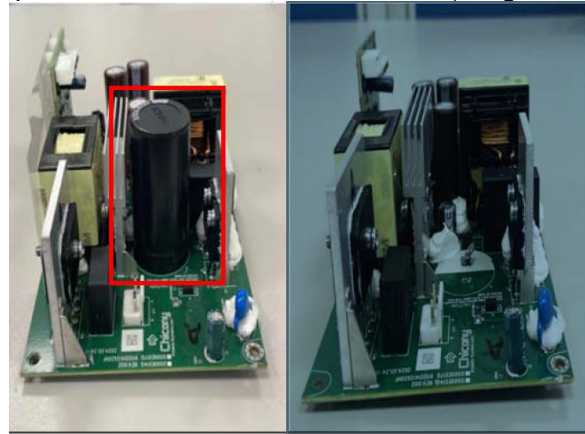
Step26. Loose the 3 screws from the rear side and remove inlet socket away from the bottom chassis.



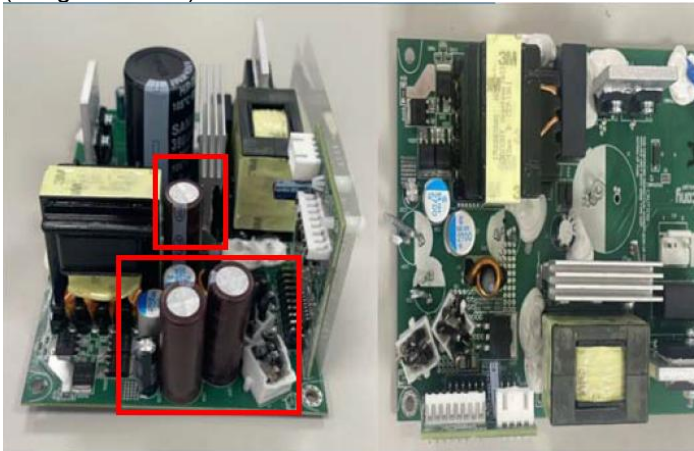
Step27 Use the screwdriver to cut off output mix cables to separate them from the PCBA.



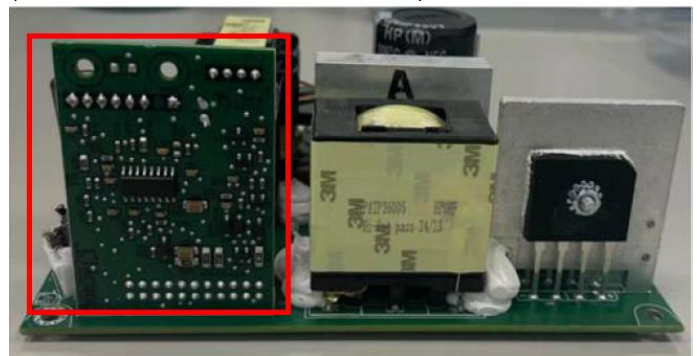
Step28, Use the screwdriver to cut off Identity electrolyte capacitor >2.5 cm for further treatment (Length: 4.8 cm).



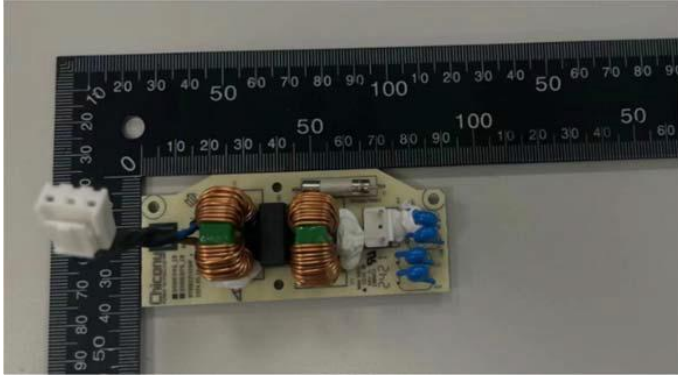
Step29, Use the screwdriver to cut off Identity electrolyte capacitor > 2.5cm for further treatment (Length: 2.5 cm).



Step30, Identity PCBA > 10 cm2 for further treatment (CTL board 1: L: 5.7cm; W: 3.9 cm).



Step31. Identity PCBA > 10 cm² for further treatment
(CTL board 2: L:9 cm; W: 3.8cm)



Step32. Identity PCBA > 10 cm² for further treatment
(CTL board 2: L: 13.5cm; W: 9cm)

